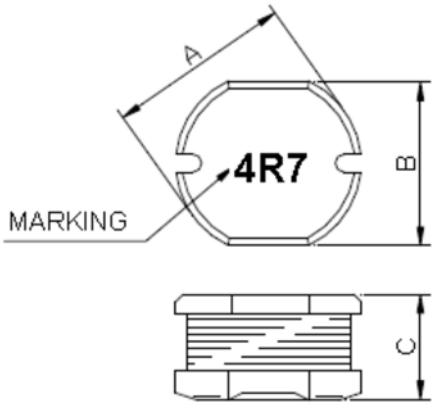
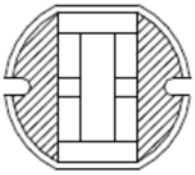
FEATRLRES

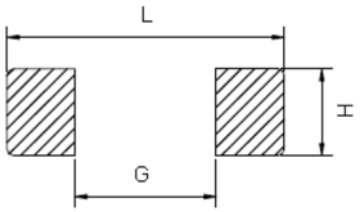
- Excellent solderability and high heat resistance.
- Excellent terminal strength construction.
- Packed in embossed carrier tape and can be used by automatic mounting machine.
- 100% Lead(Pb) & Halogen-Free and RoHS compliant.

CONFIGRLRATIONS & DIMENSIONS (unit in mm)





Recommended Land pattern



Size	A	B	C	L	G	H
HSDR32	3.50±0.3	3.00±0.3	2.10±0.3	3.7	1.1	3.3

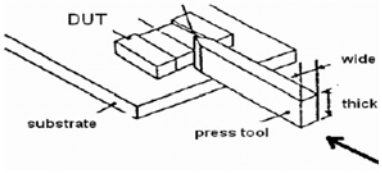
ELECTRICAL CHARACTERISTICS

Part Number	Inductance (uH)	Tolerance (%)	Test Frequency (Hz)	DCR (Ω) max.	IDC (A) max.
HSDR32-1R0M	1.0	± 20%	1V/7.96M	0.04	1.50
HSDR32-1R4M	1.4	± 20%	1V/7.96M	0.05	1.50
HSDR32-1R8M	1.8	± 20%	1V/7.96M	0.06	0.80
HSDR32-2R2M	2.2	± 20%	1V/7.96M	0.08	0.75
HSDR32-2R7M	2.7	± 20%	1V/7.96M	0.10	0.75
HSDR32-3R3M	3.3	± 20%	1V/7.96M	0.15	0.60
HSDR32-3R9M	3.9	± 20%	1V/7.96M	0.20	0.50
HSDR32-4R7M	4.7	± 20%	1V/7.96M	0.20	0.50
HSDR32-5R6M	5.6	± 20%	1V/7.96M	0.23	0.45
HSDR32-6R8M	6.8	± 20%	1V/7.96M	0.25	0.40
HSDR32-8R2M	8.2	± 20%	1V/7.96M	0.30	0.40
HSDR32-100M	10	± 20%	1V/2.52M	0.35	0.35

HSDR32-120M	12	± 20%	1V/2.52M	0.40	0.35
HSDR32-150M	15	± 20%	1V/2.52M	0.50	0.30
HSDR32-180M	18	± 20%	1V/2.52M	0.55	0.30
HSDR32-220M	22	± 20%	1V/2.52M	0.60	0.30
HSDR32-270M	27	± 20%	1V/2.52M	0.70	0.30
HSDR32-330M	33	± 20%	1V/2.52M	1.00	0.25
HSDR32-390M	39	± 20%	1V/2.52M	1.20	0.25
HSDR32-470M	47	± 20%	1V/2.52M	1.50	0.20
HSDR32-560M	56	± 20%	1V/2.52M	1.80	0.20
HSDR32-680M	68	± 20%	1V/2.52M	2.00	0.18
HSDR32-820M	82	± 20%	1V/2.52M	2.50	0.16
HSDR32-101M	100	± 20%	1V/1K	3.00	0.15
HSDR32-121M	120	± 20%	1V/1K	3.50	0.14
HSDR32-151M	150	± 20%	1V/1K	4.00	0.13
HSDR32-181M	180	± 20%	1V/1K	5.00	0.12
HSDR32-221M	220	± 20%	1V/1K	5.50	0.10
HSDR32-271M	270	± 20%	1V/1K	6.00	0.10
HSDR32-331M	330	± 20%	1V/1K	7.00	0.10
HSDR32-391M	390	± 20%	1V/1K	8.00	0.10
HSDR32-471M	470	± 20%	1V/1K	12.00	0.09

Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	
Storage temperature	1. -10~+40℃,50~60%RH (Product with taping) 2. -40~+125℃(on board)	
Electrical Performance Test		
Inductance	Refer to standard electrical characteristics list.	HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.
DCR		CH16502,Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	Approximately△L30%	Saturation DC Current (Isat) will cause L0 to drop △L(%)
Heat Rated Current (Irms)	Approximately △T40℃	Heat Rated Current (Irms) will cause the coil temperature rise △T(℃). 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer
Reliability Test		
Life Test	Appearance：No damage.	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature： 125±2℃(Inductor) Applied current：rated current Duration：1000±12hrs Measured at room temperature after placing for 24±2 hrs

<table>
<tr><td>Load Humidity</td><td rowspan="4">Inductance：within±10% of initial value
Q：Shall not exceed the specification value.
RDC：within ±15% of initial value and shall not exceed the specification value</td><td>Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles
Humidity：85±2 % R.H,
Temperature：85℃±2℃
Duration：1000hrs Min. with 100% rated current
Measured at room temperature after placing for 24±2 hrs</td></tr>
<tr><td>Moisture Resistance</td><td>Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow
Profiles
1. Baked at50℃ for 25hrs, measured at room temperature after placing for 4 hrs.
2. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs.
3. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in
2.5hrs,keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs
4. Keep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at
room temperature after placing for 1~2 hrs.</td></tr>
<tr><td>Thermal
shock</td><td>Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification
Reflow Profiles
Condition for 1 cycle
Step1：-40±2℃ 30±5min
Step2：25±2℃ ≦0.5min
Step3：125±2℃ 30±5min
Number of cycles： 500
Measured at room temperature after placing for 24±2 hrs</td></tr>
<tr><td>Vibration</td><td>Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes
Equipment： Vibration checker
Total Amplitude:1.52mm±10%
Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations)。</td></tr>
<tr><td>Bending</td><td rowspan="2">Appearance：No damage.
Impedance：within±15% of initial value
Inductance：within±10% of initial value
Q：Shall not exceed the specification value.
RDC：within ±15% of initial value and shall not exceed the specification value</td><td>Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm
<0805 inch(2012mm):40x100x0.8mm
Bending depth: >=0805 inch(2012mm):1.2mm
<0805 inch(2012mm):0.8mm
duration of 10 sec.</td></tr>
<tr><td>Shock</td><td>
<table>
<tr><th>Type</th><th>Peak value (g's)</th><th>Normal duration (D) (ms)</th><th>Wave form</th><th>Velocity change (Vi)ft/sec</th></tr>
<tr><td>SMD</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr>
<tr><td>Lead</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr>
</table>
</td></tr>
<tr><td>Solder ability</td><td>More than 95% of the terminal electrode should be covered with solder。</td><td>Preheat: 150℃,60sec.。
Solder: Sn96.5% Ag3% Cu0.5%
Temperature: 245±5℃。
Flux for lead free: Rosin. 9.5%。
Dip time: 4±1sec。
Depth: completely cover the termination</td></tr>
<tr><td>Resistance to Soldering Heat</td><td rowspan="2">Appearance：No damage.
Impedance：within±15% of initial value
Inductance：within±10% of initial value
Q：Shall not exceed the specification value.
RDC：within ±15% of initial value and shall not exceed the specification value e</td><td>Depth: completely cover the termination
<table>
<tr><th>Temperature(°C)</th><th>Time(s)</th><th>Temperature ramp/immersion and emersion rate</th><th>Number of heat cycles</th></tr>
<tr><td>260 ±5 (solder temp)</td><td>10 ±1</td><td>25mm/s ±6 mm/s</td><td>1</td></tr>
</table>
</td></tr>
<tr><td>Terminal
Strength</td><td>Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles
With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.
 
</td></tr>
</table>

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.